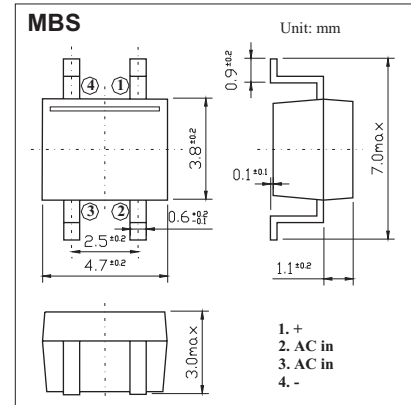


MB6S

■ Features

- Glass passivated chip junctions
- High surge current capability
- Ideal for printed circuit board



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RMM}	600	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_{DC}		
RMS Reverse Voltage	V_{RMS}	420	V
Average Forward Rectified Current	I_o	0.5	A
on glass-epoxy P.C.B. (Note 1)		0.8	
on aluminum substrate (Note 2)			
Non-Repetitive Peak Forward Surge Current, 8.3 ms Single half-sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	35	A
Forward Voltage (per element) @ $I_F = 0.4A$	V_F	1.0	V
Reverse Current(per element) @ Rated V_R	I_R	5	μA
@ $T_A = 25^\circ C$		100	
@ $T_A = 125^\circ C$			
Rating for fusing ($t < 8.3ms$)	I^2t	5.0	A^2s
Typical Total Capacitance (per element) (Note 3)	C_J	13	pF
Typical Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	85	$^\circ C/W$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 to +150	$^\circ C$

Note 1. On glass epoxy P.C.B. mounted on 0.05X0.05" (1.3X1.3mm) pads

2. On aluminum substrate P.C.B. with an area of 0.8"X0.8" (20X20mm) mounted on 0.05X0.05" (1.3 X 1.3mm) solder pad

3. Measured at 1.0 MHz and applied reverse voltage of 4.0 V

■ Marking

Marking	MB6S
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■ Typical Characteristics

